



PRODUCT DATASHEET



- PCB Side View
- ▶ 1204SV (3010) 2.0t
- Yellow (590nm)



1204SV (3010) 2.0t Compliant

FEATURES:

- Package: PCB / CHIP Side View LED
- Forward Current: 20mA
- Forward Voltage (typ.): 2.0V
- Luminous Intensity (typ.): 6mcd@20mA .
- Colour: Yellow
- Wavelength: 590nm .
- Viewing angle: 150° •
- Materials:
 - Die: GaAsP/GaP _
 - Resin: Epoxy (Water Clear)
- Operating Temperature: -40~+80°C
- Storage Temperature: -40~+85°C
- Grouping parameters: .
 - Forward voltage _
 - Luminous intensity _
 - Dominant wavelength
- Soldering methods: Reflow
- MSL Level: 3 acc. to JEDEC
- Packing: 8mm tape with max.3000/reel, ø180mm (7")

N0Y63S30SV

PCB Side View 1204SV (3010) 2.0t

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APPLICATIONS:

Backlighting

Switch light

Dashboard

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Indication Light



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	lf	30	mA
Peak Forward Current Duty 1/8@1KHz	IFP	125	mA
Revrse Voltage	V _R	5	V
Reverse Current @5V	IR	10	μΑ
Power Dissipation	PD	75	mW
Operating Temperature	Topr	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

Electrical & Optical Characteristics (Ta=25°C)

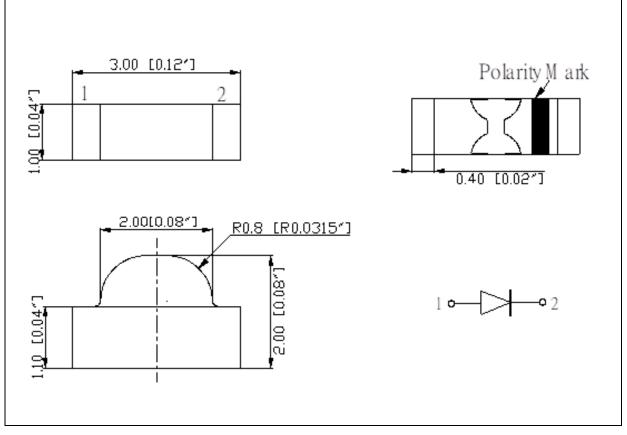
Parameter	Sumbol	Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	VF	1.7	2.0	2.5	V	I⊧=20mA
Luminous Intensity	Iv	3.2	6	20	mcd	I _F =20mA
Dominant Wavelength	λ_{D}	585	590	595	nm	I⊧=20mA
Peak Wavelength	λ_{P}		585		nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		35		nm	I⊧=20mA
Viewing Angle	20 _{1/2}		150		deg	I _F =20mA

1. Luminous intensity (Iv) ±15%, Forward Voltage (Vr) ±0.1V, Viewing angle(2 $\theta_{1/2}$) ±5%



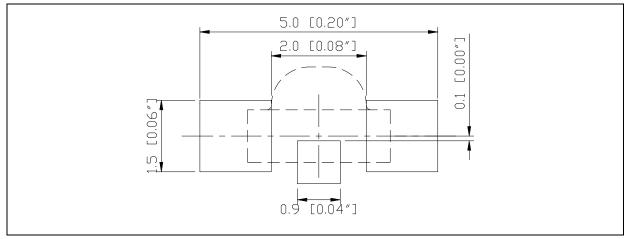
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^{\circ}$.



BINNING GROUPS:

Forward Voltage Classifications ($I_F = 20mA$):

Code	Min.	Max.	Unit
	1.7	2.5	V

Luminous Intensity Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
7	3.2	5	
8	5	8	
9	8	12.5	mcd
А	12.5	16	
В	16	20	

Dominant Wavelength Classifications (I_F = 20mA):

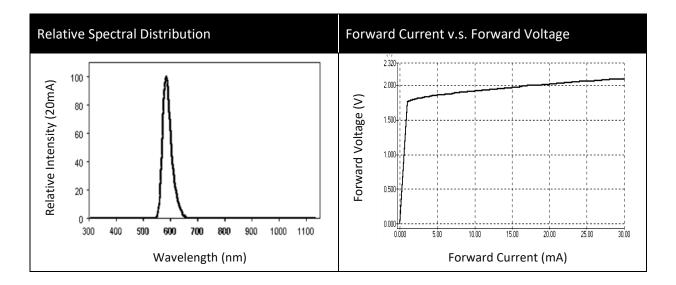
Code	Min.	Max.	Unit
m	585	590	
n	590	595	nm

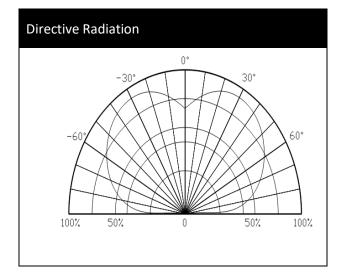
Example Group Name on Label:

• □ 8m 20 = □ (1.7~2.5V) ▶ 8 (5~8mcd) ▶ m (585~590nm) ▶ 20 (IF=20mA)



ELECTRO-OPTICAL CHARACTERISTICS:

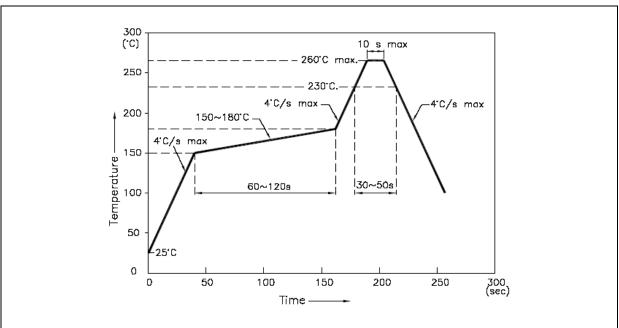




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RECOMMENDED SOLDERING PROFILE:



Reflow Solder:

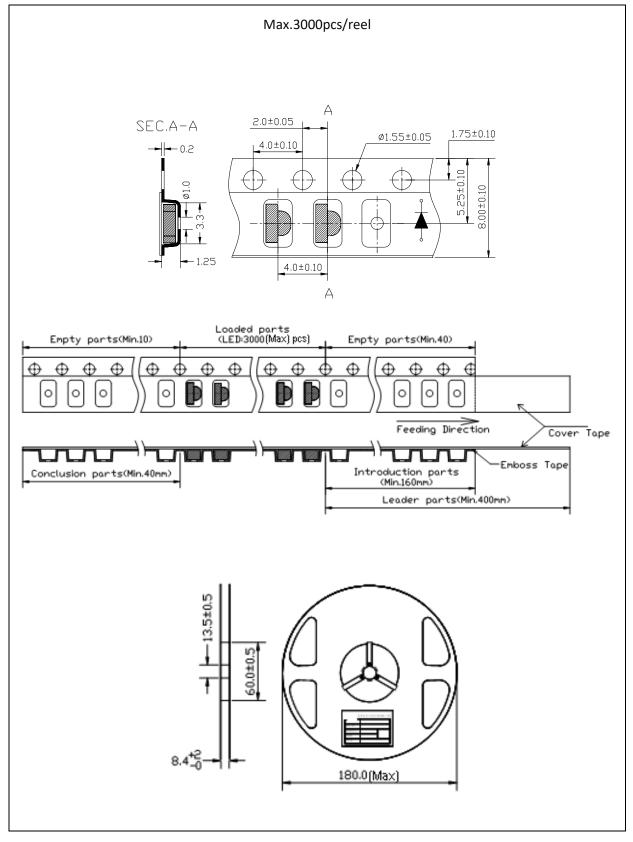
Note:

- 1. Recommend reflow temperature 245°C. The Maximum Soldering temperature should be limited to 260°C.
- 2. Maximum reflow soldering: 2 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking.

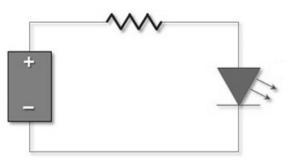
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

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REVISION RECORD:

Version	Date	Summary of Revision
A1.0	01/12/2022	Datasheet set-up.

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